

ABSTRACT

The object of the present invention is to provide a metal heater capable of quickly heating a semiconductor wafer and the
5 likewise with slight unevenness of temperature at the time of heating, and causing no warping or sagging in the metal plate employed therein.

The metal heater of the present invention comprises a metal plate and a heating element, wherein the metal plate has a thickness of 50 mm or less and a surface flatness of 50 μm or less, and an outer rim of a region where the heating element is formed is at a position within 25% of the diameter of the metal plate from an outer circumference of the metal plate.